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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

E·XFI

Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	60MHz
Connectivity	SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	32
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.25K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-VQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at89c51rc2-rltim

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

### **Block Diagram**

Figure 1. Block Diagram



- Notes: 1. Alternate function of Port 1.
  - 2. Alternate function of Port 3.



### Figure 12. PCA Interrupt System



**PCA Modules:** each one of the five compare/capture Modules has six possible functions. It can perform:

- 16-bit Capture, positive-edge triggered
- 16-bit Capture, negative-edge triggered
- 16-bit Capture, both positive and negative-edge triggered
- 16-bit Software Timer
- 16-bit High-speed Output
- 8-bit Pulse Width Modulator

In addition, Module 4 can be used as a Watchdog Timer.

Each Module in the PCA has a special function register associated with it. These registers are: CCAPM0 for Module 0, CCAPM1 for Module 1, etc. (see Table 24). The registers contain the bits that control the mode that each Module will operate in.

- The ECCF bit (CCAPMn. 0 where n = 0, 1, 2, 3, or 4 depending on the Module) enables the CCF flag in the CCON SFR to generate an interrupt when a match or compare occurs in the associated Module.
- PWM (CCAPMn. 1) enables the pulse width modulation mode.
- The TOG bit (CCAPMn. 2) when set causes the CEX output associated with the Module to toggle when there is a match between the PCA counter and the Module's capture/compare register.
- The match bit MAT (CCAPMn. 3) when set will cause the CCFn bit in the CCON register to be set when there is a match between the PCA counter and the Module's capture/compare register.
- The next two bits CAPN (CCAPMn. 4) and CAPP (CCAPMn. 5) determine the edge that a capture input will be active on. The CAPN bit enables the negative edge, and the CAPP bit enables the positive edge. If both bits are set both edges will be enabled and a capture will occur for either transition.
- The last bit in the register ECOM (CCAPMn. 6) when set enables the comparator function.

Table 24 shows the CCAPMn settings for the various PCA functions.



	Figure 19. UART Timings in N	lodes 2 and 3				
		<u> </u>				
	Start	Data byte	Ninth Stop			
	bit		bit bit			
	RI SMOD0=0					
	SMOD0=1		]			
	FE		·····			
	SMOD0=1		<i>.</i>			
Automatic Address Recognition	The automatic address recogn nication feature is enabled (SM Implemented in hardware, auto communication feature by al	ition feature is enabled w 12 bit in SCON register is omatic address recognitio lowing the serial port to	hen the multiprocessor comm set). on enhances the multiprocess examine the address of eac	u- or ch		
	incoming command frame. Or receiver sets RI bit in SCON re is not interrupted by command	nly when the serial port r gister to generate an inte frames addressed to othe	ecognizes its own address, th rrupt. This ensures that the CP er devices.	וe יU		
	If desired, the user may enable	e the automatic address	recognition feature in mode 1.	.In		
	the received command frame	address matches the dev	vice's address and is terminate	ed		
	by a valid stop bit.					
	To support automatic address a broadcast address.	recognition, a device is in	lentified by a given address ar	nd		
	Note: The multiprocessor comr be enabled in mode 0 (i.	munication and automatic a e. setting SM2 bit in SCON	ddress recognition features cann register in mode 0 has no effect).	ıot		
Given Address	Each device has an individual address that is specified in SADDR register; the SADEN register is a mask byte that contains don't-care bits (defined by zeros) to form the device's given address. The don't-care bits provide the flexibility to address one or more slaves at a time. The following example illustrates how a given address is formed. To address a device by its individual address, the SADEN mask byte must be 1111					
	For example:					
	SADDR0101 0110b SADEN1111 1100b					
	Given0101 01XXb					
	The following is an example of Slave A:SADDR1111 0001b <u>SADEN1111 1010b</u>	how to use given addres	ses to address different slaves	3:		
	Given1111 0X0Xb					
	Slave B:SADDR1111 0011b <u>SADEN1111 1001b</u>					
	Given1111 0XX1b					
	Slave C:SADDR1111 0010b <u>SADEN1111 1101b</u>					
	Given1111 00X1b					



### Table 41. PCON Register

PCON - Power Control Register (87h)

7	6	5	4	3	2	1	0	
SMOD1	SMOD0	-	POF	GF1	GF0	PD	IDL	
Bit Number	Bit Mnemonic			Desc	ription			
7	SMOD1	Serial port Set to select	<b>Mode bit 1 fo</b> t double bauc	or UART I rate in mode	1, 2 or 3.			
6	SMOD0	Serial port Cleared to s Set to selec	Serial port Mode bit 0 for UART Cleared to select SM0 bit in SCON register. Set to select FE bit in SCON register.					
5	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.					
4	POF	Power-Off Cleared to r Set by hard by software	Power-Off Flag Cleared to recognize next reset type. Set by hardware when VCC rises from 0 to its nominal voltage. Can also be set by software.					
3	GF1	General pu Cleared by Set by user	General purpose Flag Cleared by user for general purpose usage. Set by user for general purpose usage.					
2	GF0	General pu Cleared by Set by user	General purpose Flag Cleared by user for general purpose usage. Set by user for general purpose usage.					
1	PD	Power-Dow Cleared by I Set to enter	Power-Down mode bit Cleared by hardware when reset occurs. Set to enter power-down mode.					
0	IDL	Idle mode I Cleared by Set to enter	<b>bit</b> nardware whe idle mode.	en interrupt or	reset occurs.			

Reset Value = 00X1 0000b Not bit addressable

Power-off flag reset value will be 1 only after a power on (cold reset). A warm reset doesn't affect the value of this bit.





### Table 42. BDRCON Register

BDRCON - Baud Rate Control Register (9Bh)

7	6	5	4	3	2	1	0			
-	-	-	BRR	ТВСК	RBCK	SPD	SRC			
Bit Number	Bit Mnemonic	Descriptior	1							
7	-	Reserved The value re	ead from this	bit is indeterm	inate. Do not s	set this bit				
6	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit							
5	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.							
4	BRR	Baud Rate Cleared to s Set to start t	Baud Rate Run Control bit Cleared to stop the internal Baud Rate Generator. Set to start the internal Baud Rate Generator.							
3	ТВСК	Transmissi Cleared to s Set to selec	Transmission Baud rate Generator Selection bit for UART Cleared to select Timer 1 or Timer 2 for the Baud Rate Generator. Set to select internal Baud Rate Generator.							
2	RBCK	Reception Cleared to s Set to selec	Reception Baud Rate Generator Selection bit for UART Cleared to select Timer 1 or Timer 2 for the Baud Rate Generator. Set to select internal Baud Rate Generator.							
1	SPD	Baud Rate Cleared to s Set to selec	Baud Rate Speed Control bit for UART Cleared to select the SLOW Baud Rate Generator. Set to select the FAST Baud Rate Generator.							
0	SRC	<b>Baud Rate Source select bit in Mode 0 for UART</b> Cleared to select F <sub>OSC</sub> /12 as the Baud Rate Generator (F <sub>CLK PERIPH</sub> /6 in X2 mode). Set to select the internal Baud Rate Generator for UARTs in mode 0.								

Reset Value = XXX0 0000b Not bit addressablef

### Table 46. IPH0 Register

IPH0 - Interrupt Priority High Register (B7h)

7	6	5	4	3	2	1	0
-	PPCH	PT2H	PSH	PT1H	PX1H	PT0H	PX0H
Bit Number	Bit Mnemonic	Description					
7	-	<b>Reserved</b> The value re	ad from this b	it is indetermi	nate. Do not s	et this bit.	
6	РРСН	PCA Interru           PPCHPPCL           0         0           1         0           1         1	<b>pt Priority Hi</b> <u>Priority Lev</u> Lowest Highest	gh Bit <u>/el</u>			
5	PT2H	Timer 2 Ove           PT2HPT2L           0         0           0         1           1         0           1         1	erflow Interru <u>Priority Lev</u> Lowest Highest	pt Priority Hi <u>/el</u>	gh Bit		
4	PSH	Serial Port F           PSH         PSL           0         0           0         1           1         0           1         1	Priority High <u>Priority Lev</u> Lowest Highest	Bit /el			
3	PT1H	Timer 1 Ove           PT1HPT1L           0         0           0         1           1         0           1         1	e <b>rflow Interru</b> <u>Priority Lev</u> Lowest Highest	pt Priority Hi <u>/el</u>	gh Bit		
2	PX1H	<b>External Inte</b> <u>PX1HPX1L</u> 0 0 0 1 1 0 1 1	errupt 1 Prio Priority Lev Lowest Highest	rity High Bit /el			
1	РТОН	Timer 0 Ove           PT0HPT0L           0         0           0         1           1         0           1         1	rflow Interru <u>Priority Lev</u> Lowest Highest	pt Priority Hi <u>/el</u>	gh Bit		
0	PX0H	External Internation           PX0H PX0L           0         0           0         1           1         0           1         1	errupt 0 Prior Priority Lev Lowest Highest	rity High Bit /el			

Reset Value = X000 0000b Not bit addressable





# Serial Port Interface The Serial communication

The Serial Peripheral Interface Module (SPI) allows full-duplex, synchronous, serial communication between the MCU and peripheral devices, including other MCUs.

Features

### Features of the SPI Module include the following:

- Full-duplex, three-wire synchronous transfers
- Master or Slave operation
- Eight programmable Master clock rates
- Serial clock with programmable polarity and phase
- Master Mode fault error flag with MCU interrupt capability
- Write collision flag protection

Signal DescriptionFigure 25 shows a typical SPI bus configuration using one Master controller and many<br/>Slave peripherals. The bus is made of three wires connecting all the devices.

Figure 25. SPI Master/Slaves Interconnection



The Master device selects the individual Slave devices by using four pins of a parallel port to control the four  $\overline{SS}$  pins of the Slave devices.

Master Output Slave Input<br/>(MOSI)This 1-bit signal is directly connected between the Master Device and a Slave Device.<br/>The MOSI line is used to transfer data in series from the Master to the Slave. Therefore,<br/>it is an output signal from the Master, and an input signal to a Slave. A Byte (8-bit word)<br/>is transmitted most significant bit (MSB) first, least significant bit (LSB) last.

Master Input Slave Output<br/>(MISO)This 1-bit signal is directly connected between the Slave Device and a Master Device.<br/>The MISO line is used to transfer data in series from the Slave to the Master. Therefore,<br/>it is an output signal from the Slave, and an input signal to the Master. A Byte (8-bit<br/>word) is transmitted most significant bit (MSB) first, least significant bit (LSB) last.

**SPI Serial Clock (SCK)** This signal is used to synchronize the data movement both in and out of the devices through their MOSI and MISO lines. It is driven by the Master for eight clock cycles which allows to exchange one Byte on the serial lines.

Slave Select (SS)Each Slave peripheral is selected by one Slave Select pin (SS). This signal must stay<br/>low for any message for a Slave. It is obvious that only one Master (SS high level) can

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As shown in Figure 28, the first SCK edge is the MSB capture strobe. Therefore, the Slave must begin driving its data before the first SCK edge, and a falling edge on the  $\overline{SS}$  pin is used to start the transmission. The  $\overline{SS}$  pin must be toggled high and then low between each Byte transmitted (Figure 30).

Figure 29 shows an SPI transmission in which CPHA is '1'. In this case, the Master begins driving its MOSI pin on the first SCK edge. Therefore, the Slave uses the first SCK edge as a start transmission signal. The SS pin can remain low between transmissions (Figure 30). This format may be preffered in systems having only one Master and only one Slave driving the MISO data line.



Bit Number	Bit Mnemonic	Description
1	-	<b>Reserved</b> The value read from this bit is indeterminate. Do not set this bit.
0	-	<b>Reserved</b> The value read from this bit is indeterminate. Do not set this bit.

Reset Value = 00X0 XXXXb

Not Bit addressable

Serial Peripheral DATa Register (SPDAT) The Serial Peripheral Data Register (Table 58) is a read/write buffer for the receive data register. A write to SPDAT places data directly into the shift register. No transmit buffer is available in this model.

A Read of the SPDAT returns the value located in the receive buffer and not the content of the shift register.

### Table 58. SPDAT Register

SPDAT - Serial Peripheral Data Register (0C5H)

7	6	5	4	3	2	1	0
R7	R6	R5	R4	R3	R2	R1	R0

Reset Value = Indeterminate

R7:R0: Receive data bits

SPCON, SPSTA and SPDAT registers may be read and written at any time while there is no on-going exchange. However, special care should be taken when writing to them while a transmission is on-going:

- Do not change SPR2, SPR1 and SPR0
- Do not change CPHA and CPOL
- Do not change MSTR
- Clearing SPEN would immediately disable the peripheral
- Writing to the SPDAT will cause an overflow.



Table 60. WDTPRG Register

WDTPRG - Watchdog Timer Out Register (0A7h)

7	6	5	4	3	2	1	0			
-	-	-	-	-	S2	S1	S0			
Bit Number	Bit Mnemonic	Description								
7	-									
6	-									
5	-	Reserved The value rea	ad from this bi	t is undetermir	ned. Do not tr	y to set this bit	i.			
4	-									
3	-									
2	S2	WDT Time-o	ut Select Bit	2						
1	S1	WDT Time-o	ut Select Bit	1						
0	S0	WDT Time-o	ut Select Bit	0						
		S2         S1           0         0           0         1           0         1           1         0           1         1           1         1           1         1	$\begin{array}{c} \underline{\textbf{S0Selected}}\\ 0(2^{14} - 1) \text{ m}\\ 1(2^{15} - 1) \text{ m}\\ 0(2^{16} - 1) \text{ m}\\ 1(2^{17} - 1) \text{ m}\\ 0(2^{18} - 1) \text{ m}\\ 1(2^{19} - 1) \text{ m}\\ 0(2^{20} - 1) \text{ m}\\ 1(2^{21} - 1) \text{ m}\\ \end{array}$	<u>I Time-out</u> achine cycles nachine cycles nachine cycles nachine cycles nachine cycles nachine cycles nachine cycles	, 16. 3 ms @ , 32.7 ms @ F s, 65. 5 ms @ , 131 ms @ F , 262 ms @ F s, 542 ms @ F , 1.05 s @ F <sub>0</sub> s, 2.09 s @ F <sub>0</sub>	$F_{OSCA} = 12 \text{ M}$ $F_{OSCA} = 12 \text{ M}$ $F_{OSCA} = 12 \text{ M}$ $OSCA = 12 \text{ M}$ $OSCA = 12 \text{ M}$ $F_{OSCA} = 12 \text{ M}$ $SCA = 12 \text{ M}$ $SCA = 12 \text{ M}$	Hz Iz IHz z z Iz			

Reset Value = XXXX X000

## WDT During Power-down and Idle

In Power-down mode the oscillator stops, which means the WDT also stops. While in Power-down mode the user does not need to service the WDT. There are two methods of exiting Power-down mode: by a hardware reset or via a level activated external interrupt which is enabled prior to entering Power-down mode. When Power-down is exited with hardware reset, servicing the WDT should occur as it normally should whenever the AT89C51RB2/RC2 is reset. Exiting Power-down with an interrupt is significantly different. The interrupt is held low long enough for the oscillator to stabilize. When the interrupt is brought high, the interrupt is serviced. To prevent the WDT from resetting the device while the interrupt pin is held low, the WDT is not started until the interrupt is pulled high. It is suggested that the WDT be reset during the interrupt service routine.

To ensure that the WDT does not overflow within a few states of exiting of power-down, it is better to reset the WDT just before entering power-down.

In the Idle mode, the oscillator continues to run. To prevent the WDT from resetting the AT89C51RB2/RC2 while in Idle mode, the user should always set up a timer that will periodically exit Idle, service the WDT, and re-enter Idle mode.

MEL

Flash EEPROM Memory	The Flash memory increases EPROM and ROM functionality with in-circuit electrical erasure and programming. It contains 16K or 32K Bytes of program memory organized in 128 or 256 pages of 128 Bytes. This memory is both parallel and serial In-system Pro- grammable (ISP). ISP allows devices to alter their own program memory in the actual end product under software control. A default serial loader (bootloader) program allows ISP of the Flash.					
	The programming does not require external dedicated programming voltage. The necessary high programming voltage is generated on-chip using the standard $V_{\rm CC}$ pins of the microcontroller.					
Features	Flash EEPROM internal program memory.					
	• Boot vector allows user provided Flash loader code to reside anywhere in the Flash memory space. This configuration provides flexibility to the user.					
	• Default loader in Boot ROM allows programming via the serial port without the need of a user-provided loader.					
	<ul> <li>Up to 64K Byte external program memory if the internal program memory is disabled (EA = 0).</li> </ul>					
	<ul> <li>Programming and erase voltage with standard 5V or 3V V<sub>CC</sub> supply.</li> <li>Read/Programming/Erase: <ul> <li>Byte-wise read without wait state</li> <li>Byte or page erase and programming (10 ms)</li> </ul> </li> <li>Typical programming time (32K Bytes) in 10 s</li> <li>Parallel programming with 87C51 compatible hardware interface to programmer</li> <li>Programmable security for the code in the Flash</li> <li>100K write cycles</li> <li>10 years data retention</li> </ul>					
Flash Programming and Erasure	The 16K or 32K Bytes Flash is programmed by Bytes or by pages of 128 Bytes. It is not necessary to erase a Byte or a page before programming. The programming of a Byte or a page includes a self erase before programming.					
	<ul> <li>There are three methods of programming the Flash memory:</li> <li>First, the on-chip ISP bootloader may be invoked which will use low level routines to program the pages. The interface used for serial downloading of Flash is the UART.</li> <li>Second, the Flash may be programmed or erased in the end-user application by calling low-level routines through a common entry point in the Boot ROM.</li> <li>Third, the Flash may be programmed using the parallel method by using a conventional EPROM programmer. The parallel programming method used by these devices is similar to that used by EPROM 87C51 but it is not identical and the commercially available programmers need to have support for the AT89C51RB2/RC2. The bootloader and the Application Programming Interface (API) routines are located in the BOOT ROM.</li> </ul>					

### **Bootloader Functionality**

Introduction

The bootloader can be activated by two means: Hardware conditions or regular boot process.

The Hardware conditions (EA = 1, PSEN = 0) during the Reset# falling edge force the on-chip bootloader execution. This allows an application to be built that will normally execute the end user's code but can be manually forced into default ISP operation.

As PSEN is an output port in normal operating mode (running user application or boorloader code) after reset, it is recommended to release PSEN after falling edge of reset signal. The hardware conditions are sampled at reset signal falling edge, thus they can be released at any time when reset input is low.

To ensure correct microcontroller startup, the PSEN pin should not be tied to ground during power-on (See Figure 38).

Figure 38. Hardware conditions typical sequence during power-on.



The on-chip bootloader boot process is shown in Figure 39.

	Purpose
Hardware Conditions	The Hardware Conditions force the bootloader execution whatever BLJB, BSB and SBV values.
	The Boot Loader Jump Bit forces the application execution. BLJB = 0 => Boot loader execution. BLJB = 1 => Application execution.
BLJB	The BLJB is a fuse bit in the Hardware Byte.
	That can be modified by hardware (programmer) or by software (API).
	Note:
	The BLJB test is perform by hardware to prevent any program execution.
	The Software Boot Vector contains the high address of custumer bootloader stored in the application.
SBV	SBV = FCh (default value) if no custumer bootloader in user Flash.
	Note:
	The costumer bootloader is called by JMP [SBV]00h instruction.



## AIMEL

### **Autobaud Performances**

The ISP feature allows a wide range of baud rates in the user application. It is also adaptable to a wide range of oscillator frequencies. This is accomplished by measuring the bit-time of a single bit in a received character. This information is then used to program the baud rate in terms of timer counts based on the oscillator frequency. The ISP feature requires that an initial character (an uppercase U) be sent to the AT89C51RB2/RC2 to establish the baud rate. Table 72 shows the autobaud capability.

Frequency (MHz)										
Baudrate (bit/s)	1.8432	2	2.4576	3	3.6864	4	5	6	7.3728	8
2400	OK	ОК	ОК	ОК	ОК	OK	OK	ОК	ОК	OK
4800	OK	-	ОК	ОК	ОК	ОК	ОК	ОК	ОК	OK
9600	ОК	-	ОК	ОК	ОК	ОК	ОК	ОК	ОК	OK
19200	OK	-	ОК	ОК	ОК	-	-	ОК	ОК	OK
38400	-	-	ОК		ОК	-	ОК	ОК	ОК	
57600	-	-	-	-	ОК	-	-	-	ОК	
115200	-	-	-	-	-	-	-	-	ОК	
Frequency (MHz)										
Baudrate (bit/s)	10	11.0592	12	14.318	14.746	16	20	24	26.6	
2400	OK	ок	ок	ок	ОК	ОК	ОК	ок	ОК	
4800	ОК	ОК	ОК	ОК	ОК	ОК	ОК	ОК	ОК	
9600	ОК	ок	ОК	ОК	ОК	ОК	ОК	ОК	ОК	
19200	ОК	ок	ОК	ОК	ОК	ОК	ОК	ОК	ОК	
38400	-	ОК	ОК	ОК	ОК	ОК	ОК	ОК	ОК	
57600	-	ОК	-	ОК	ОК	ОК	ОК	ОК	ОК	
115200	-	ОК	-	OK	OK	-	-	-	-	

### Table 72. Autobaud Performances

## Command Data Stream Protocol

All commands are sent using the same flow. Each frame sent by the host is echoed by the bootloader.



### $T_A = -40^{\circ}C$ to $+85^{\circ}C$ ; $V_{SS} = 0V$ ;

 $V_{CC}$  =2.7V to 5.5V and F = 0 to 40 MHz (both internal and external code execution)

 $V_{CC}$  =4.5V to 5.5V and F = 0 to 60 MHz (internal code execution only) (Continued)

Symbol	Parameter	Min	Тур	Мах	Unit	Test Conditions
V <sub>OH1</sub>	Output High Voltage, port 0, ALE, PSEN	V <sub>CC</sub> - 0.3 V <sub>CC</sub> - 0.7 V <sub>CC</sub> - 1.5			V V V	$V_{CC} = 5V \pm 10\%$ $I_{OH} = -200 \ \mu A$ $I_{OH} = -3.2 \ m A$ $I_{OH} = -7.0 \ m A$
		0.9 V <sub>CC</sub>			V	VCC = 2.7V to 5.5V $I_{OH}$ = -10 $\mu$ A
R <sub>RST</sub>	RST Pulldown Resistor	50	200 <sup>(5)</sup>	250	kΩ	
I <sub>IL</sub>	Logical 0 Input Current ports 1, 2, 3, 4 and 5			-50	μΑ	V <sub>IN</sub> = 0.45V
I <sub>LI</sub>	Input Leakage Current for P0 only			±10	μΑ	$0.45 \mathrm{V} < \mathrm{V_{IN}} < \mathrm{V_{CC}}$
I <sub>TL</sub>	Logical 1 to 0 Transition Current, ports 1, 2, 3, 4			-650	μΑ	V <sub>IN</sub> = 2.0V
C <sub>IO</sub>	Capacitance of I/O Buffer			10	pF	Fc = 3 MHz TA = 25°C
I <sub>PD</sub>	Power Down Current		100	150	μΑ	$4.5V < V_{CC <} 5.5V^{(3)}$
I <sub>CCOP</sub>	Power Supply Current on normal mode			0.4 x Frequency (MHz) + 5	mA	$V_{CC} = 5.5 V^{(1)}$
	Power Supply Current on idle mode			0.3 x Frequency (MHz) + 5	mA	$V_{CC} = 5.5 V^{(1)}$
I <sub>CCProg</sub>	Power Supply Current during flash Write / Erase		0.4 x Frequency (MHz) + 20		mA	V <sub>CC</sub> = 5.5V <sup>(8)</sup>

Notes: 1. Operating I<sub>CC</sub> is measured with all output pins disconnected; XTAL1 driven with  $T_{CLCH}$ ,  $T_{CHCL}$  = 5 ns (see Figure 49.),  $V_{IL}$  =  $V_{SS}$  + 0.5V,

 $V_{IH} = V_{CC} - 0.5V$ ; XTAL2 N.C.;  $\overline{EA} = RST = Port 0 = V_{CC}$ .  $I_{CC}$  would be slightly higher if a crystal oscillator used (see Figure 46).

- 2. Idle I<sub>CC</sub> is measured with all output pins disconnected; XTAL1 driven with T<sub>CLCH</sub>, T<sub>CHCL</sub> = 5 ns, V<sub>IL</sub> = V<sub>SS</sub> + 0.5V, V<sub>IH</sub> = V<sub>CC</sub> 0.5V; XTAL2 N.C; Port 0 = V<sub>CC</sub>; EA = RST = V<sub>SS</sub> (see Figure 47).
- Power Down I<sub>CC</sub> is measured with all output pins disconnected; EA = V<sub>SS</sub>, PORT 0 = V<sub>CC</sub>; XTAL2 NC.; RST = V<sub>SS</sub> (see Figure 48).
- 4. Capacitance loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V<sub>OL</sub>s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1 to 0 transitions during bus operation. In the worst cases (capacitive loading 100pF), the noise pulse on the ALE line may exceed 0.45V with maxi V<sub>OL</sub> peak 0.6V. A Schmitt Trigger use is not necessary.
- 5. Typical are based on a limited number of samples and are not guaranteed. The values listed are at room temperature and 5V.

 Under steady state (non-transient) conditions, I<sub>OL</sub> must be externally limited as follows: Maximum I<sub>OL</sub> per port pin: 10 mA Maximum I<sub>OL</sub> per 8-bit port: Port 0: 26 mA Ports 1, 2 and 3: 15 mA

Maximum total  $I_{OL}$  for all output pins: 71 mA

If  $I_{OL}$  exceeds the test condition,  $V_{OL}$  may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

- 7. For other values, please contact your sales office.
- 8. Icc Flash Write operation current while an on-chip flash page write is on going.
- 9. Flash Retention is guaranteed with the same formula for  $V_{cc}$  Min down to 0.

### 108 **AT89C51RB2/RC2**

## DC Parameters for Low Voltage

TA = 0°C to +70°C; V<sub>SS</sub> = 0V; V<sub>CC</sub> = 2.7V to 3.6V; F = 0to 40 MHz TA = -40°C to +85°C; V<sub>SS</sub> = 0V; V<sub>CC</sub> = 2.7V to 3.6V; F = 0 to 40 MHz

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
V <sub>IL</sub>	Input Low Voltage	-0.5		0.2 V <sub>CC</sub> - 0.1	V	
V <sub>IH</sub>	Input High Voltage except RST, XTAL1	0.2 V <sub>CC</sub> + 0.9		V <sub>CC</sub> + 0.5	V	
V <sub>IH1</sub>	Input High Voltage, RST, XTAL1	0.7 V <sub>CC</sub>		V <sub>CC</sub> + 0.5	V	
V <sub>OL</sub>	Output Low Voltage, ports 1, 2, 3, 4 <sup>(6)</sup>			0.45	V	I <sub>OL</sub> = 0.8 mA <sup>(4)</sup>
V <sub>OL1</sub>	Output Low Voltage, port 0, ALE, PSEN (6)			0.45	V	I <sub>OL</sub> = 1.6 mA <sup>(4)</sup>
V <sub>OH</sub>	Output High Voltage, ports 1, 2, 3, 4	0.9 V <sub>CC</sub>			V	I <sub>OH</sub> = -10 μA
V <sub>OH1</sub>	Output High Voltage, port 0, ALE, PSEN	0.9 V <sub>CC</sub>			V	I <sub>OH</sub> = -40 μA
I <sub>IL</sub>	Logical 0 Input Current ports 1, 2, 3, 4			-50	μΑ	V <sub>IN</sub> = 0.45 V
I <sub>LI</sub>	Input Leakage Current for P0 only			±10	μΑ	$0.45 \mathrm{V} < \mathrm{V_{IN}} < \mathrm{V_{CC}}$
I <sub>TL</sub>	Logical 1 to 0 Transition Current, ports 1, 2, 3,			-650	μA	V <sub>IN</sub> = 2.0V
R <sub>RST</sub>	RST Pulldown Resistor	50	200 (5)	250	kΩ	
C <sub>IO</sub>	Capacitance of I/O Buffer			10	pF	Fc = 3 MHz TA = 25°C
I <sub>PD</sub>	Power Down Current		10 <sup>(5)</sup>	50	μA	$V_{CC} = 2.7V$ to $3.6V^{(3)}$
I <sub>CCOP</sub>	Power Supply Current on normal mode			0.4 x Frequency (MHz) + 5	mA	$V_{\rm CC} = 3.6 \ V^{(1)}$
	Power Supply Current on idle mode			0.3 x Frequency (MHz) + 5	mA	V <sub>CC</sub> = 3.6 V <sup>(2)</sup>
I <sub>CCProg</sub>	Power Supply Current during flash Write / Erase		0.4 x Frequency (MHz) + 20		mA	V <sub>CC</sub> = 5.5V <sup>(8)</sup>

Notes: 1. Operating I<sub>CC</sub> is measured with all output pins disconnected; XTAL1 driven with T<sub>CLCH</sub>, T<sub>CHCL</sub> = 5 ns (see Figure 49.), V<sub>IL</sub> = V<sub>SS</sub> + 0.5V,

 $V_{IH} = V_{CC} - 0.5V$ ; XTAL2 N.C.;  $\overline{EA} = RST = Port 0 = V_{CC}$ .  $I_{CC}$  would be slightly higher if a crystal oscillator used (see Figure 46).

- 2. Idle  $I_{CC}$  is measured with all output pins disconnected; XTAL1 driven with  $T_{CLCH}$ ,  $T_{CHCL} = 5$  ns,  $V_{IL} = V_{SS} + 0.5V$ ,  $V_{IH} = V_{CC} 0.5V$ ; XTAL2 N.C; Port 0 =  $V_{CC}$ ; EA = RST =  $V_{SS}$  (see Figure 47).
- Power Down I<sub>CC</sub> is measured with all output pins disconnected; EA = V<sub>SS</sub>, PORT 0 = V<sub>CC</sub>; XTAL2 NC.; RST = V<sub>SS</sub> (see Figure 48).
- 4. Capacitance loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V<sub>OL</sub>s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1 to 0 transitions during bus operation. In the worst cases (capacitive loading 100pF), the noise pulse on the ALE line may exceed 0.45V with maxi V<sub>OL</sub> peak 0.6V. A Schmitt Trigger use is not necessary.
- 5. Typical are based on a limited number of samples and are not guaranteed. The values listed are at room temperature and 5V.
- Under steady state (non-transient) conditions, I<sub>OL</sub> must be externally limited as follows: Maximum I<sub>OL</sub> per port pin: 10 mA Maximum I<sub>OL</sub> per 8-bit port: Port 0: 26 mA Ports 1, 2 and 3: 15 mA Maximum total I<sub>OL</sub> for all output pins: 71 mA



### **AC Parameters**

Explanation of the AC Symbols	Each timing symbol has 5 characters. The first character is always a "T" (stands for time). The other characters, depending on their positions, stand for the name of a signal or the logical status of that signal. The following is a list of all the characters and what they stand for. Example: $T_{AVLL}$ = Time for Address Valid to ALE Low. $T_{LLPL}$ = Time for ALE Low to PSEN Low.
	(Load Capacitance for port 0, ALE and PSEN = 100 pF; Load Capacitance for all other outputs = 80 pF.)
	Table 75 Table 78, and Table 80 give the description of each AC symbols.
	Table 77, Table 79 and Table 81 give the AC parameterfor each range.
	Table 76, Table 77 and Table 82 gives the frequency derating formula of the AC parameter for each speed range description. To calculate each AC symbols, take the x value in the correponding column (-M or -L) and use this value in the formula.
	Example: $T_{LLIU}$ for -M and 20 MHz, Standard clock. x = 35 ns T 50 ns $T_{CCIV}$ = 4T - x = 165 ns
External Program Memory	Table 75. Symbol Description

### Characteristics

### Table 75. Symbol Description

Symbol	Parameter
т	Oscillator clock period
T <sub>LHLL</sub>	ALE pulse width
T <sub>AVLL</sub>	Address Valid to ALE
T <sub>LLAX</sub>	Address Hold after ALE
T <sub>LLIV</sub>	ALE to Valid Instruction In
T <sub>LLPL</sub>	ALE to PSEN
T <sub>PLPH</sub>	PSEN Pulse Width
T <sub>PLIV</sub>	PSEN to Valid Instruction In
T <sub>PXIX</sub>	Input Instruction Hold after PSEN
T <sub>PXIZ</sub>	Input Instruction Float after PSEN
T <sub>AVIV</sub>	Address to Valid Instruction In
T <sub>PLAZ</sub>	PSEN Low to Address Float



### External Program Memory Read Cycle



### External Data Memory Characteristics

Table 78. Symbol Description

Symbol	Parameter
T <sub>RLRH</sub>	RD Pulse Width
T <sub>WLWH</sub>	WR Pulse Width
T <sub>RLDV</sub>	RD to Valid Data In
T <sub>RHDX</sub>	Data Hold After RD
T <sub>RHDZ</sub>	Data Float After RD
T <sub>LLDV</sub>	ALE to Valid Data In
T <sub>AVDV</sub>	Address to Valid Data In
T <sub>LLWL</sub>	ALE to WR or RD
T <sub>AVWL</sub>	Address to WR or RD
T <sub>QVWX</sub>	Data Valid to WR Transition
T <sub>QVWH</sub>	Data set-up to WR High
T <sub>WHQX</sub>	Data Hold After WR
T <sub>RLAZ</sub>	RD Low to Address Float
T <sub>WHLH</sub>	RD or WR High to ALE high



### PLC44



	Ν	1M ·	IN	СН
A	4.20	4. 57	. 165	. 180
A1	2. 29	3.04	. 090	. 120
D	17.40	17.65	. 685	. 695
D1	16.44	16.66	, 647	. 656
D2	14.99	16.00	. 590	. 630
E	17.40	17.65	. 685	. 695
E1	16.44	16.66	. 647	. 656
E5	14.99	16.00	. 590	. 630
e	1.27	BSC	. 050	BSC
G	1.07	1.22	. 042	. 048
н	1.07	1.42	. 042	. 056
J	0.51	-	. 020	-
К	0.33	0.53	. 013	. 021
Nd	11		1	1
Ne	11		1	1
PKG STD 0		00		

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